Amendments to the Specification:

Please replace the paragraph beginning at page 20, line 2 with the following rewritten paragraph:

A $LiTaO_3$ substrate may be encircled by $LiTaO_3$, as described above, to suppress decomposition of Li. By heating the $LiTaO_3$ substrate, thus encircled by the Li-containing material, it is possible to suppress the decomposition of the $LiTaO_3$ substrate. As for a $SrTiO_3$ substrate, it may be encircled by sintered pieces of $SrTiO_3$, as described above, to suppress decomposition of Sr. In such case, decomposition of the $SrTiO_3$ substrate may be suppressed by encircling the substrate with the Sr containing material, followed by heating. As for the $LiGaO_2$ substrate, it may be encircled with sintered $LiGaO_2$ to suppress the decomposition of Li. In such case, decomposition of the $LiGaO_2$ substrate may be suppressed by encircling the substrate with the Li containing material followed by heating. As for the MgO substrate, it may be encircled with sintered MgO to suppress the decomposition of Mg. In such case, decomposition of the MgO substrate may be suppressed by encircling the substrate with the Mg containing material followed by heating. As for the $LiAlO_2$ substrate, it may be encircled with sintered $LiAlO_2$ to suppress the decomposition of Li. In such case, decomposition of the $LiAlO_2$ substrate may be suppressed by encircling the substrate with the Li containing material followed by heating. As for the $LaSrAlTaO_3$ substrate, it may be encircled with the sintered $LaSrAlTaO_3$ to suppress the decomposition of La. In such case, decomposition of the $LaSrAlTaO_3$ substrate may be suppressed by encircling the substrate with the La containing material followed by heating.